

Version with Markings to Show Changes Made

The specification has been amended as follows:

At page 1, after the title, the following paragraph has been inserted:

--This application is a divisional of U.S. Patent Application Serial No. 09/606,583, filed on June 29, 2000 by Mark Kenneth Hoffmeyer et al. and entitled "PROCESSING OF CIRCUIT BOARDS WITH PROTECTIVE, ADHESIVE-LESS COVERS ON AREA ARRAY BONDING SITES," the disclosure of which is incorporated by reference herein.--

The claims have been amended as follows:

Claims 1-10 and 13-18 have been canceled.

Claims 11-12 and 19-22 remain and are currently pending as follows:

11. An assembly comprising:

2 a circuit board;
3 an area array bonding site on a surface of the circuit board; and
4 a protective cover overlaying the bonding site, the protective cover removably
5 registered to the bonding site by a plurality of posts secured to one of the protective cover
6 and the circuit board into a plurality of apertures disposed in the other of the protective
7 cover and the circuit board.

1 12. The assembly of claim 11, wherein the protective cover includes an adhesiveless
2 surface contacting the bonding site.

1 19. A cover for protecting an area array bonding site on a surface of a circuit board, the
2 circuit board having a plurality of apertures, the cover comprising:
3 a base member having a first face and second face, the base member shaped to at

1 least correspond to said area array bonding site; and
2 a plurality of posts coupled to the first face and registered for said plurality of
3 apertures.

1 20. The cover of claim 19, wherein the first face of the base member further includes
2 a recess corresponding to said area array bonding site.

1 21. The cover of claim 19, further comprising:
2 a graspable extension coupled to the second face of the base member.

1 22. The cover of claim 19, wherein each of the plurality of posts includes a diametral
2 slot.